

2019 Sensor Production



Sensor #	Received	Tested	V dep (V) CNM	Av. Edge (um), UCSC	V break (V) CNM	V break (V) UCSC	Pinholes Sector A	Pinholes Sector B	Baking	Nitride on the back?	Glued to Hybrid	Goodness	Current Location	Notes
W01-S4	01/13/2019				120	120	93, 207, 227, 249, 44, 76, 96, 124, 138, 142, 170, 204	98		No	gimp	gimp	SLAC	
W07-S2	02/27/2019	UCSC-baking2	30	397	60	30	143, 173, 16, 150, 198	1, 21, 71, 103, 217, 102	171 C for 27 h on 2019/03/11	Yes		NG	UCSC (03/08 /19)	GP2; got worse after baking
W07-S3	02/27/2019	UCSC	23	367	380	130	194	165, 199, 88, 200		Yes	L0M02	Used	module	GP2
W07-S5	02/27/2019	UCSC-baking2	30	327	420	335	117, 127, 128	43, 156, 164, 212	171 C for 27 h on 2019/03/11	Yes	L0M10	Good Candidate	SLAC (03/14 /19)	GP2, improved a lot after baking
W07-S6	02/27/2019	UCSC-baking2	23	345	150	40	192, 194	13	171 C for 27 h on 2019/03/11	Yes		NG	UCSC (03/08 /19)	GP2; slimmed down on short side; got worse after slimming and baking
W09-S2	02/27/2019	UCSC-baked2	23	360 (399)	240	~300	159, 197, 8, 44, 188	73	171 C for 27 h on 2019/03/11	Yes	L0M07 L1ta	Good Candidate	SLAC (03/14 /19)	GP2, improved a lot after baking
W09-S5	02/27/2019	UCSC	23	342	120	120	27, 86, 100, 116	100		Yes	L0M01	Used	module	GP2
W02-S1	02/27/2019	UCSC Baked	20	416 (452)	50	180	4	24	170 C for 23 h	Yes		No, edge too wide; nitride was scrapped on the back side --> to IV (COMPLETE)	UCSC (03/08 /19)	GP1, Displaced in Gelpack
W02-S4	02/27/2019	UCSC Baked	23	331	150	135	35, 221, 138	29, 77, 98	170 C for 23 h	Yes	L0M04	Candidate	SLAC (03/08 /19)	GP1, Displaced in Gelpack
W03-S6	02/27/2019	UCSC Baked	18	328	280	190	44, 186, 200	149, 213, 36, 58	170 C for 23 h	Yes	L0M08	Candidate	SLAC (03/08 /19)	GP1, Displaced in Gelpack
W04-S3	02/27/2019	UCSC	25	349	350	370	97, 187, 227, 52, 172	49, 123, 86		Yes	L0M09	Good candidate	SLAC (03/08 /19)	GP1, In Gelpack with displaced chips
W04-S6	02/27/2019	UCSC	18	304 (340)	480	420	51, 218	40, 48, 90		Yes	L0M12	Good candidate	SLAC (03/08 /19)	GP1, In Gelpack with displaced chips

